

N-Channel 20V (D-S) MOSFET

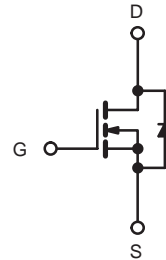
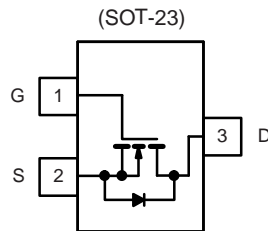
| PRODUCT SUMMARY | | | |
|---------------------|---------------------------------|------------------------------------|-----------------------|
| V _{DS} (V) | R _{DS(on)} (Ω) | I _D (A) ^{a, g} | Q _g (Typ.) |
| 20 | 0.014 at V _{GS} = 4.5V | 8 | 9nC |
| | 0.018 at V _{GS} = 2.5V | 7 | |

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Gen III Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT



N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted | | | |
|---|-----------------------------------|------------------------|---------------------|
| Parameter | Symbol | Limit | Unit |
| Drain-Source Voltage | V _{DS} | 20 | V |
| Gate-Source Voltage | V _{GS} | ± 12 | |
| Continuous Drain Current (T _J = 150 °C) | I _D | T _C = 25 °C | 8 ^{a, g} |
| | | T _C = 70 °C | 5.5 ^g |
| | | T _A = 25 °C | 6 ^{b, c} |
| | | T _A = 70 °C | 3.5 ^{b, c} |
| Pulsed Drain Current | I _{DM} | 30 ^g | A |
| Avalanche Current | I _{AS} | 14 | |
| Avalanche Energy | E _{AS} | 11.25 | mJ |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | 3 ^{a, g} |
| | | T _A = 25 °C | 1.5 ^{b, c} |
| Maximum Power Dissipation | P _D | T _C = 25 °C | 3.2 |
| | | T _C = 70 °C | 1.8 |
| | | T _A = 25 °C | 2.2 ^{b, c} |
| | | T _A = 70 °C | 1.0 ^{b, c} |
| Operating Junction and Storage Temperature Range | T _J , T _{stg} | - 55 to 150 | °C |
| Soldering Recommendations (Peak Temperature) ^{d, e} | | 260 | |

| THERMAL RESISTANCE RATINGS | | | | | |
|---|--------------|-------------------|---------|---------|------|
| Parameter | | Symbol | Typical | Maximum | Unit |
| Maximum Junction-to-Ambient ^{b, f} | t ≤ 10 s | R _{thJA} | 29 | 36 | °C/W |
| Maximum Junction-to-Case (Drain) | Steady State | R _{thJC} | 3.6 | 4.5 | |

Notes:

- Based on T_C = 25 °C.
- Surface Mounted on 1" x 1" FR4 board.
- t = 10 s.
- The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- Maximum under Steady State conditions is 81 °C/W.
- Package limited.

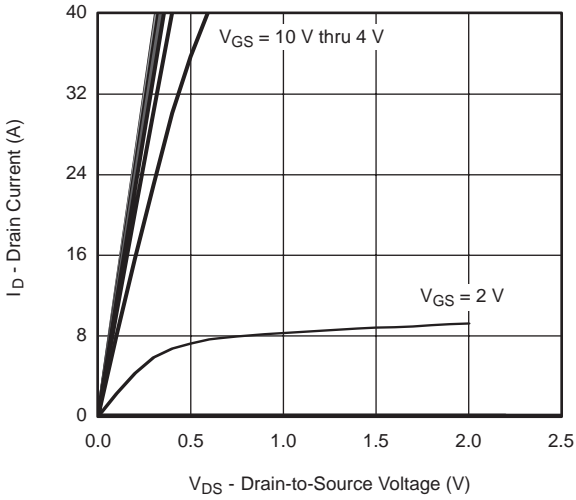
| SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted | | | | | | |
|---|-------------------------|--|------|-------|-----------|----------------------|
| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | 20 | | | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | $I_D = 250\text{ }\mu\text{A}$ | | 22 | | mV/ $^\circ\text{C}$ |
| $V_{GS(th)}$ Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | | - 5.0 | | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | 0.5 | | 1.5 | V |
| Gate-Source Leakage | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}$ | | | 1 | μA |
| | | $V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$ | | | 5 | |
| On-State Drain Current ^a | $I_{D(on)}$ | $V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$ | 12 | | | A |
| Drain-Source On-State Resistance ^a | $R_{DS(on)}$ | $V_{GS} = 4.5\text{ V}, I_D = 10\text{ A}$ | | 0.014 | | Ω |
| | | $V_{GS} = 2.5\text{ V}, I_D = 7\text{ A}$ | | 0.018 | | |
| Forward Transconductance ^a | g_{fs} | $V_{DS} = 10\text{ V}, I_D = 10\text{ A}$ | | 26 | | S |
| Dynamic^b | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$ | | 865 | | pF |
| Output Capacitance | C_{oss} | | | 316 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 131 | | |
| Total Gate Charge | Q_g | $V_{DS} = 10\text{ V}, V_{GS} = 10\text{ V}, I_D = 10\text{ A}$ | | 15 | 23 | nC |
| | | $V_{DS} = 15\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 10\text{ A}$ | | 10 | | |
| Gate-Source Charge | Q_{gs} | | 2.5 | | | |
| Gate-Drain Charge | Q_{gd} | | 2.3 | | | |
| Gate Resistance | R_g | $f = 1\text{ MHz}$ | 0.2 | 0.9 | 1.8 | Ω |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 10\text{ V}, R_L = 2\text{ }\Omega$ $I_D \cong 5\text{ A}, V_{GEN} = 4.5\text{ V}, R_g = 1\text{ }\Omega$ | | 15 | 30 | ns |
| Rise Time | t_r | | | 11 | 22 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 16 | 30 | |
| Fall Time | t_f | | | 8 | 16 | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 10\text{ V}, R_L = 2\text{ }\Omega$ $I_D \cong 5\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$ | | 10 | 20 | |
| Rise Time | t_r | | | 8 | 16 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 16 | 30 | |
| Fall Time | t_f | | | 7 | 14 | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Source-Drain Diode Current | I_S | $T_C = 25\text{ }^\circ\text{C}$ | | 8 | | A |
| Pulse Diode Forward Current | I_{SM} | | | 30 | | |
| Body Diode Voltage | V_{SD} | $I_S = 3\text{ A}, V_{GS} = 0\text{ V}$ | | 0.77 | 1.2 | V |
| Body Diode Reverse Recovery Time | t_{rr} | $I_F = 10\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$ | | 14 | 28 | ns |
| Body Diode Reverse Recovery Charge | Q_{rr} | | | 4.5 | 9 | nC |
| Reverse Recovery Fall Time | t_a | | | 5.5 | | ns |
| Reverse Recovery Rise Time | t_b | | | 8.5 | | |

Notes:

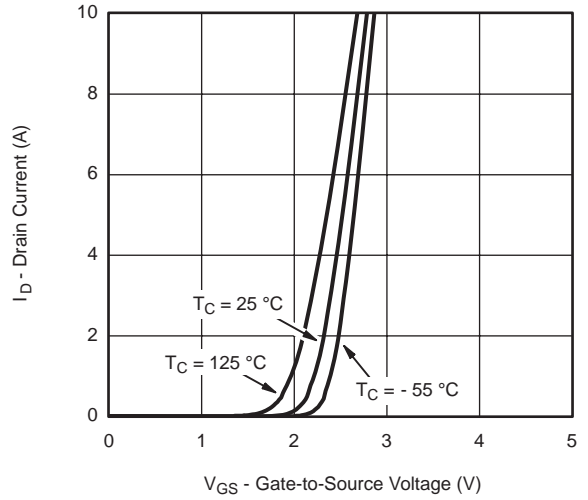
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
 b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

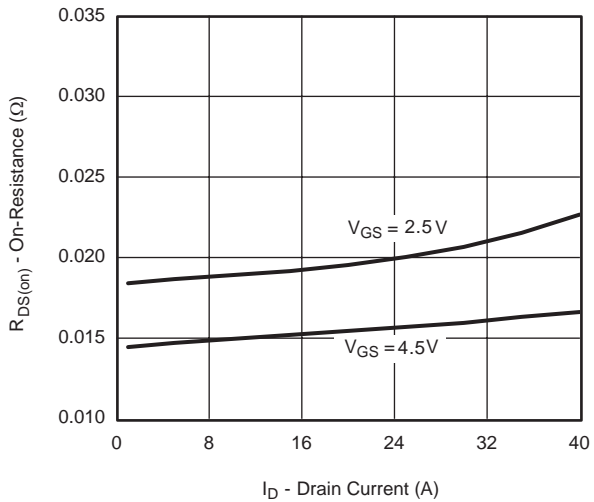
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



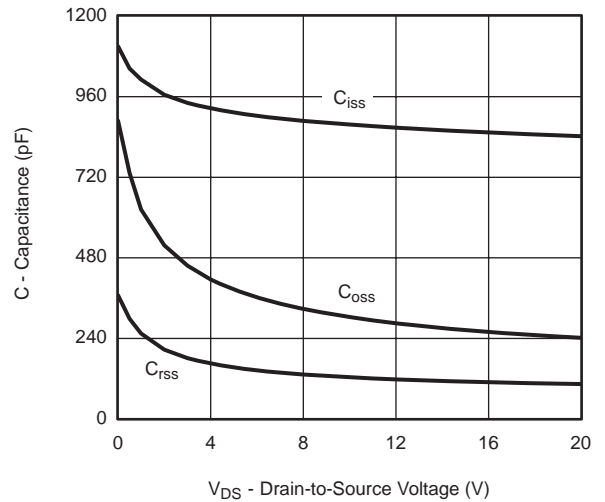
Output Characteristics



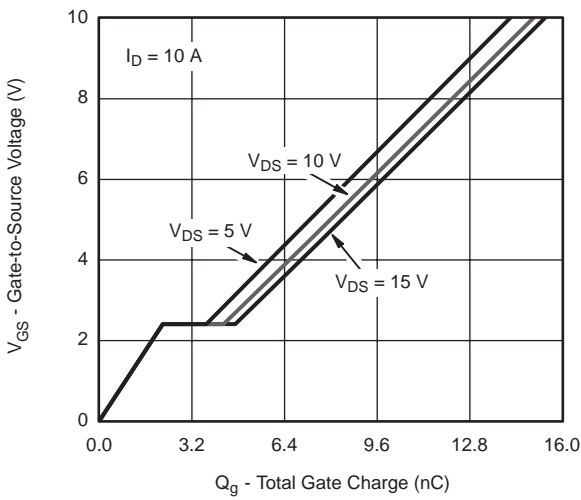
Transfer Characteristics



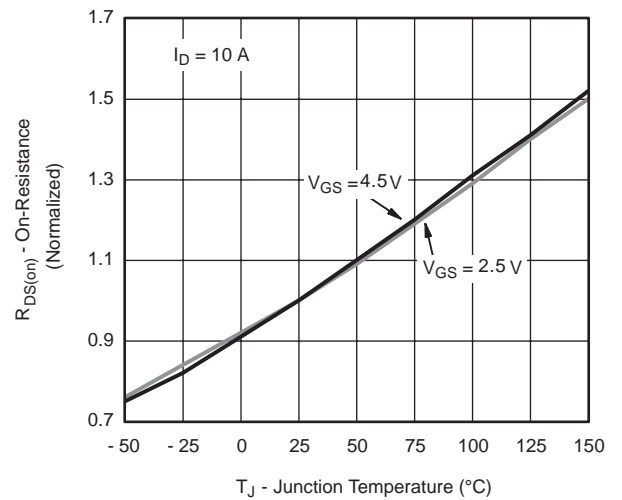
On-Resistance vs. Drain Current



Capacitance

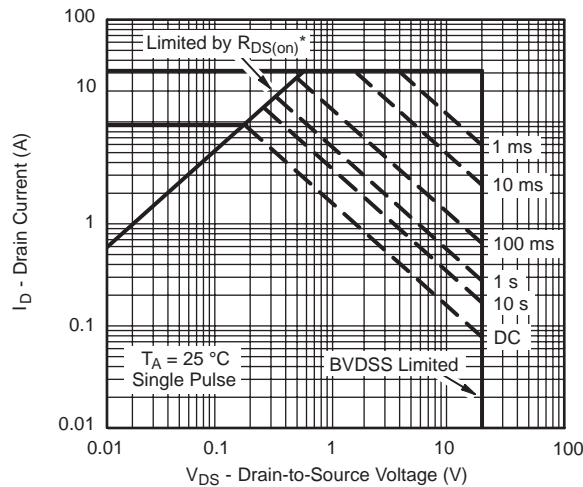
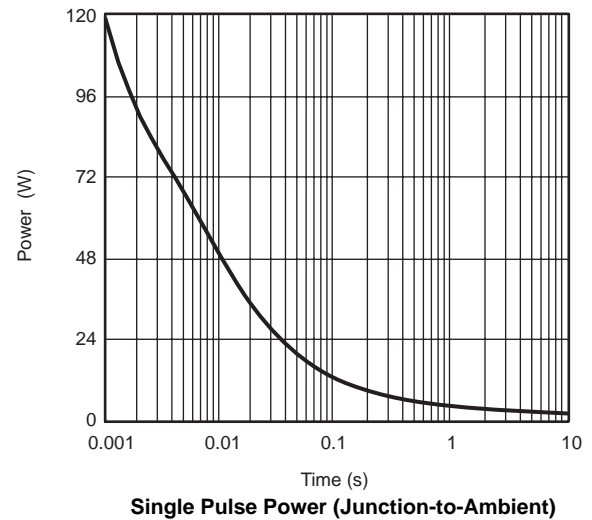
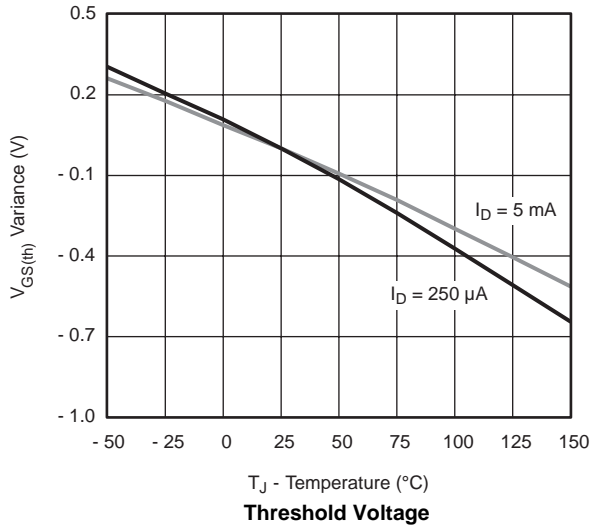
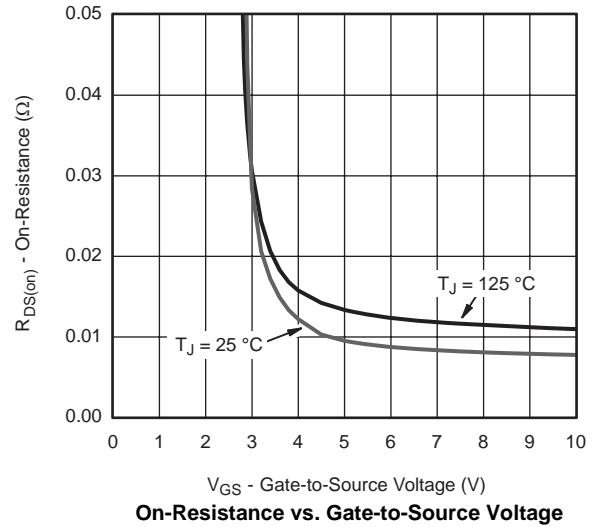
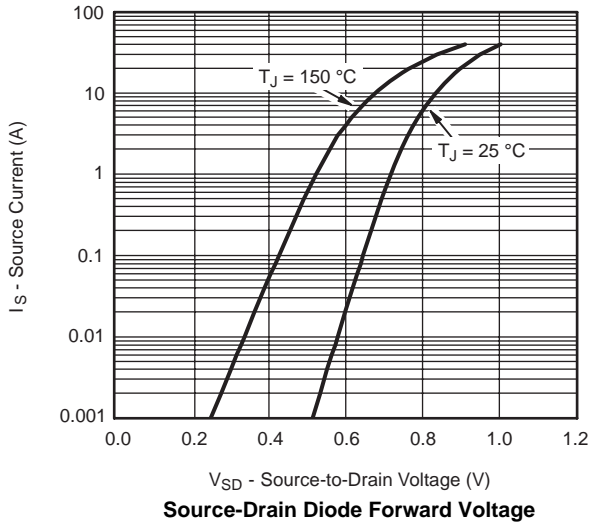


Gate Charge



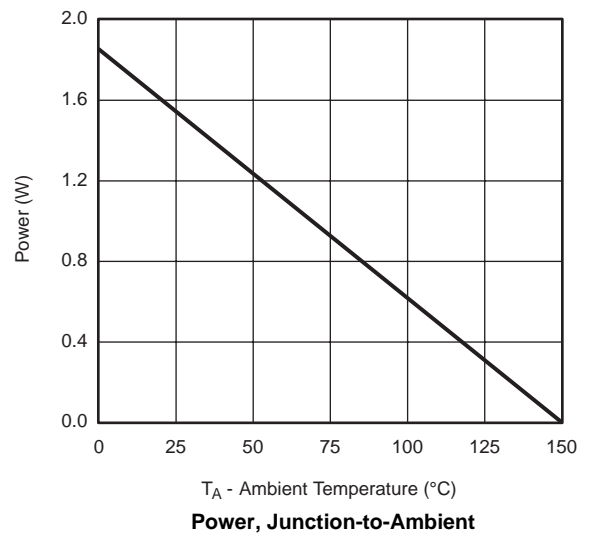
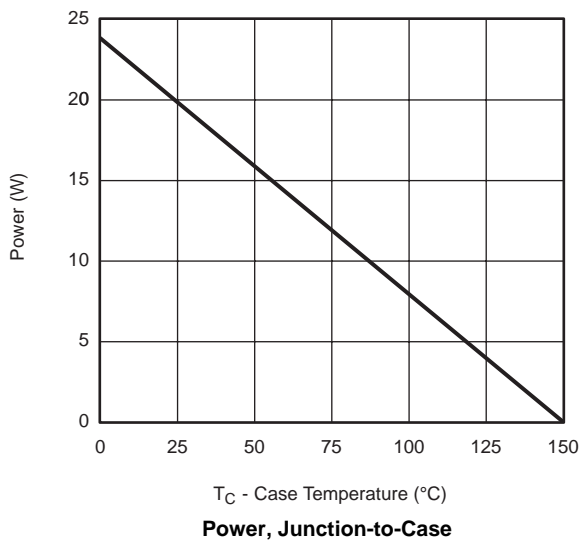
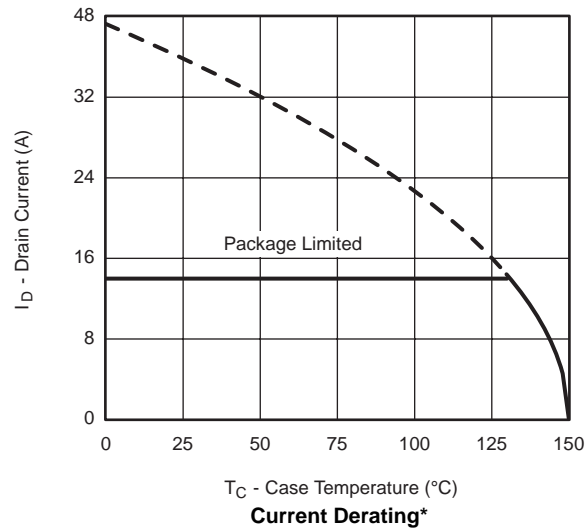
On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



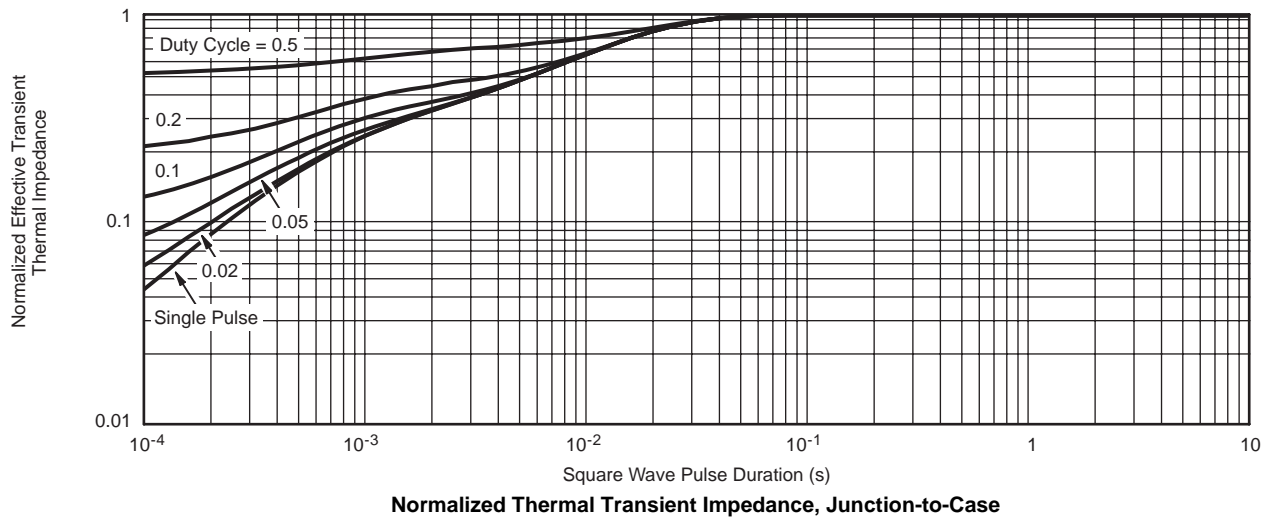
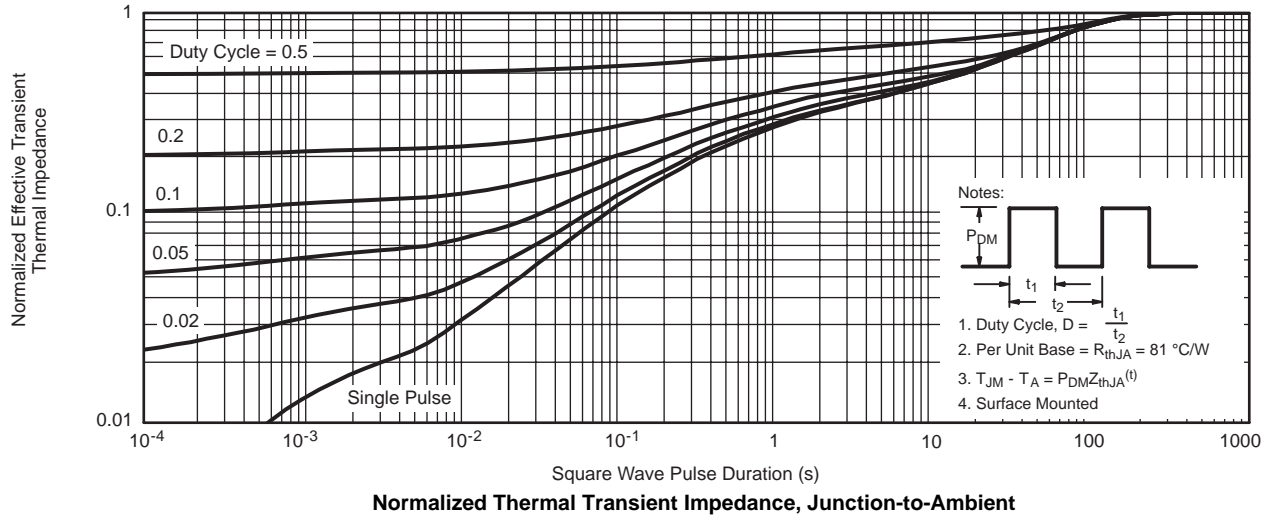
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified
Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)} = 150\text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



SOT-23 : 3-LEAD



| Dim | MILLIMETERS | | INCHES | |
|----------------|-------------|------|------------|-------|
| | Min | Max | Min | Max |
| A | 0.89 | 1.12 | 0.035 | 0.044 |
| A ₁ | 0.01 | 0.10 | 0.0004 | 0.004 |
| A ₂ | 0.88 | 1.02 | 0.0346 | 0.040 |
| b | 0.35 | 0.50 | 0.014 | 0.020 |
| c | 0.085 | 0.18 | 0.003 | 0.007 |
| D | 2.80 | 3.04 | 0.110 | 0.120 |
| E | 2.10 | 2.64 | 0.083 | 0.104 |
| E ₁ | 1.20 | 1.40 | 0.047 | 0.055 |
| e | 0.95 BSC | | 0.0374 Ref | |
| e ₁ | 1.90 BSC | | 0.0748 Ref | |
| L | 0.40 | 0.60 | 0.016 | 0.024 |
| L ₁ | 0.64 Ref | | 0.025 Ref | |
| S | 0.50 Ref | | 0.020 Ref | |
| q | 3° | 8° | 3° | 8° |

ECN: S-03946-Rev. K, 09-Jul-01
DWG: 5479

RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads
Dimensions in Inches/(mm)

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